

**Amendments to the Specification:**

Please delete the paragraph beginning on page 1, line 24.

Please replace the paragraph beginning on page 3, line 18 with the following amended paragraph:

In an example embodiment according to the present invention, in a ball grid array package (BGA) at a ball location is coupled to a grounding location for a pair of die stacked on top of each other. Referring to FIG. 1, a package assembly 100 includes a substrate 105 with a ball assembly 145 providing electrical connection to a package-bonding pad 140 through conductive traces (not illustrated). A first die 120a is attached to the substrate 105 with an adhesive 110. The adhesive may be both film and liquid. Alternatives to adhesive may include soldering or eutectic die attach. Placed on top of the first die 120a is a second die 120b. The dies 120 are electrically coupled via a conductive adhesive 115. The circuit may be designed so that the second die 120b is smaller in area by predetermined amount than that of the first die 120a and that there is accommodation made in the first die 120a for placement of the second die 120b. The accommodation may include, but is not limited to, electrical bond pads to couple the underside of the second die 120b to the first die 120a. An insulating film (refer to FIGS. 5A and 5B) may be placed between the with two die with appropriate openings defined therein to only allow the conductive adhesive 115 to bond in regions in which electrical contact is desired. Bond wires 125 couple ground pads on dies 120 to bonding pad 140. In a completed package assembly 100, a molding compound 135 seals the electrical circuit from the outside environment.

Please replace the paragraph beginning on page 4, line 3 with the following amended paragraph:

In another example embodiment, the second die 120b may have a metallization (not shown) applied to the underside to enhance the conductivity of the ground

connection facilitated by the conductive adhesive. Such metallization would likely be applied during the latter stages of wafer fabrication, after completion of the final topside passivation.

Please replace the paragraph beginning on page 4, line 7 with the following amended paragraph:

Referring to FIGS. 2A and 2B. Die 200 has an arrangement of bond pads 210. In applying an embodiment of the present invention, during the design and layout process, the circuit ~~205~~ may be arranged to have interior pads 205 connected to ground in the core area of the die, as well as the typical bond pads ~~215~~ 210. The interior pads 205 may be laid out to make optimum use of the core area. The interior pads 205 ~~locations~~ may be located at the center (as illustrated in FIG. 2B) or be offset from the center at appropriately defined areas.

Please replace the paragraph beginning on page 4, line 13 with the following amended paragraph:

Referring to FIG. 3, in an example embodiment, on a device die 300, the grounding pads 325 are located near the bond pads 310. Layer 327 is an insulating mask that exposes the grounding pads 325 but protects the die 300 from unintended ground connections after the application of a conductive adhesive 449 such as shown in ~~FIG. 4A~~ FIG. 5A.

Please replace the paragraph beginning on page 5, line 8 with the following amended paragraph:

Referring to FIG. 8, in an example embodiment, in place of grounding pads 515, a conductive grid ~~530-630~~ may be laid across the die and be coupled to bonding pads defined as ground. The defining of grounded bonding pads may be part of the device's design process. The second die ~~520-620~~ on its underside may then be bonded with

conductive adhesive to couple the second die ~~520-620~~ to the ground. The conductive grid ~~530-630~~ may be a suitable conductor, such as copper, aluminum, gold, silver, and alloys thereof. Cost and process dictate which metal is suitable. Furthermore, the coefficient of thermal expansion (CTE) is ~~a important~~ important to material choice in that materials chosen should have similar CTE. Dissimilar CTE of the materials that build a package would ultimately lead to premature mechanical failure.

Please replace the paragraph beginning on page 5, line 26 with the following amended paragraph:

Referring to FIG. 9, in another example embodiment, a device ~~600-900~~ may have a first die 905 and a second die 945 coupled together at ground a designated bonding pads 920a, 920b, and 920c chosen from the bonding pads 910a, 910b, and 910c. In this example, the first die 905 may have staggered bond pads in two rings, pads 910a and pads 910b. As mentioned earlier, these grounding pads would be designated during the design phase of the first die 905 and the second die 945. Conductive straps 930a, 930b, and 930c couple the electrical grounding of die 905 and 945 by their connection to grounded bonding pads 920a, 920b, and 920c. Sample, pad landings 960 connect the bonding pads 910a, 910b, 910c with bond wires 955. A number of these pad landings 960 are defined as ground. These multiple connections make for a robust ground. Likewise, in another example embodiment, the present invention may be used to make robust power connections. Having both robust ground and power connections reduces the multi-chip device's susceptibility to noise, such as ground bounce during bus switching.